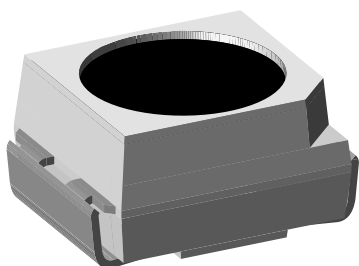


## Silicon PIN Photodiode



### DESCRIPTION

VEMD3160FX01 is a high speed and high sensitive PIN photodiode with a highly linear photoresponse.

### FEATURES

- Package type: surface-mount
- Package form: PLCC-2
- Dimensions (L x W x H in mm): 3.5 x 2.8 x 1.75
- Daylight blocking filter
- AEC-Q101 qualified
- Excellent  $I_{ra}$  linearity
- Fast response times
- Angle of half sensitivity:  $\phi = \pm 60^\circ$
- Floor life: 168 h, MSL 3, according to J-STD-020
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### APPLICATIONS

- High speed photo detector
- Small signal detection
- Proximity sensors

### PRODUCT SUMMARY

COMPONENT	$I_{ra}$ ( $\mu A$ )	$\phi$ ( $^\circ$ )	$\lambda_{0.5}$ (nm)
VEMD3160FX01	1.6	$\pm 60$	860 to 1030

#### Note

- Test conditions see table "Basic Characteristics"

### ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VEMD3160FX01-GS08	Tape and reel	MOQ: 7500 pcs, 1500 pcs/reel	PLCC-2

#### Note

- MOQ: minimum order quantity

### ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25^\circ C$ , unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Junction temperature		$T_J$	110	$^\circ C$
Ambient temperature range		$T_{amb}$	-40 to +110	$^\circ C$
Storage temperature range		$T_{stg}$	-40 to +110	$^\circ C$
Soldering temperature	According to reflow solder profile	$T_{sd}$	260	$^\circ C$

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 50\text{ mA}$	$V_F$	-	0.9	-	V
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$ , $E = 0$	$V_{(BR)}$	20	-	-	V
Reverse dark current	$V_R = 5\text{ V}$ , $E = 0$	$I_{ro}$	-	1	3	nA
Diode capacitance	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$	$C_D$	-	1.9	-	pF
	$V_R = 3\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$	$C_D$	-	1	-	pF
Temperature coefficient of $I_{ra}$	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 940\text{ nm}$	$TK_{I_{ra}}$	-	0.26	-	%/K
Reverse light current	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 940\text{ nm}$ , $V_R = 5\text{ V}$	$I_{ra}$	1.14	1.6	2.25	$\mu\text{A}$
	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 890\text{ nm}$ , $V_R = 5\text{ V}$	$I_{ra}$	-	1.5	-	$\mu\text{A}$
Angle of half sensitivity		$\phi$	-	$\pm 60$	-	$^{\circ}$
Wavelength of peak sensitivity		$\lambda_p$	-	920	-	nm
Range of spectral bandwidth		$\lambda_{0.5}$	-	860 to 1030	-	nm
Rise time	$V_R = 10\text{ V}$ , $R_L = 50\text{ }\Omega$ , $\lambda = 950\text{ nm}$	$t_r$	-	180	-	ns
Fall time	$V_R = 10\text{ V}$ , $R_L = 50\text{ }\Omega$ , $\lambda = 950\text{ nm}$	$t_f$	-	180	-	ns

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

Basic characteristics graphs to be extended to  $110\text{ }^{\circ}\text{C}$  ambient temperatures where applicable.

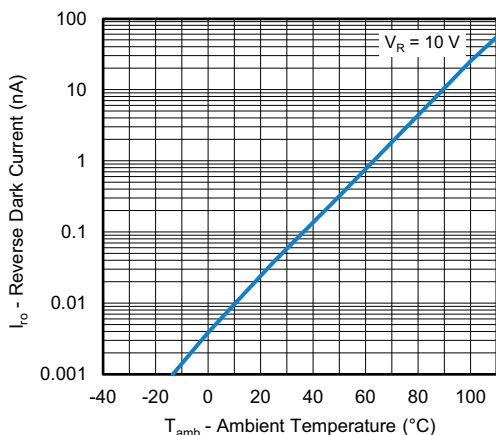


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

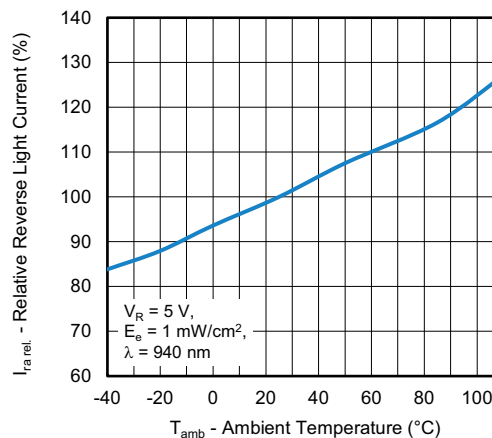


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

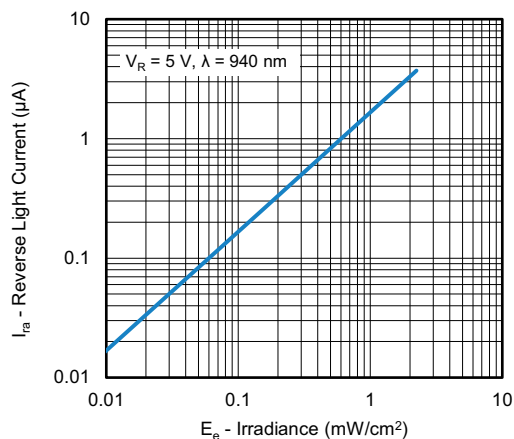


Fig. 3 - Reverse Light Current vs. Irradiance

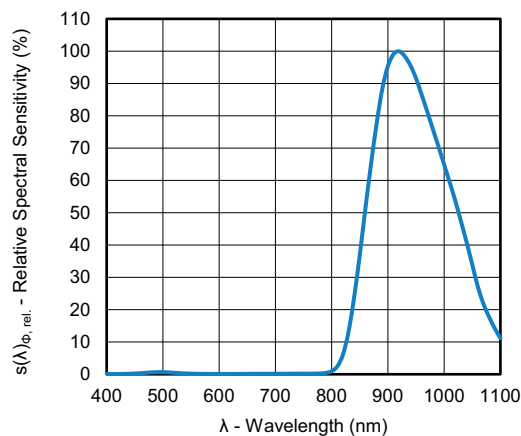


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

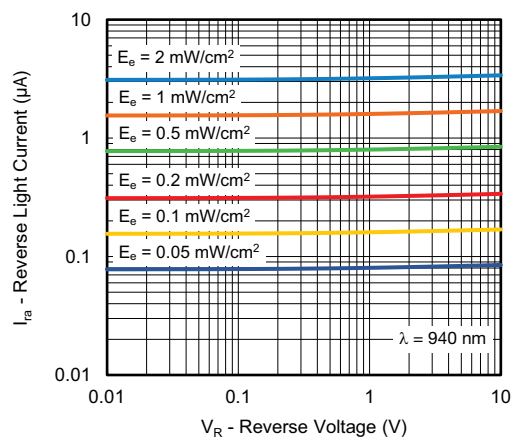


Fig. 4 - Reverse Light Current vs. Reverse Voltage

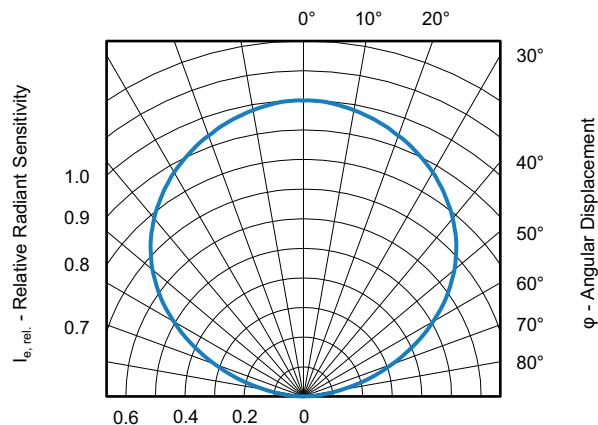


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

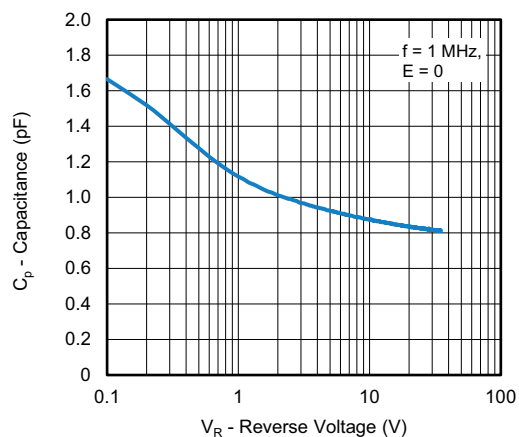


Fig. 5 - Diode Capacitance vs. Reverse Voltage

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions:  $T_{amb} < 30\text{ }^{\circ}\text{C}$ , RH < 60 %

Moisture sensitivity level 3, according to J-STD-033D.

## DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or label. Devices taped on reel dry using recommended conditions 192 h at  $40\text{ }^{\circ}\text{C}$  (+ 5  $^{\circ}\text{C}$ ), RH < 5 %.

## REFLOW SOLDER PROFILE

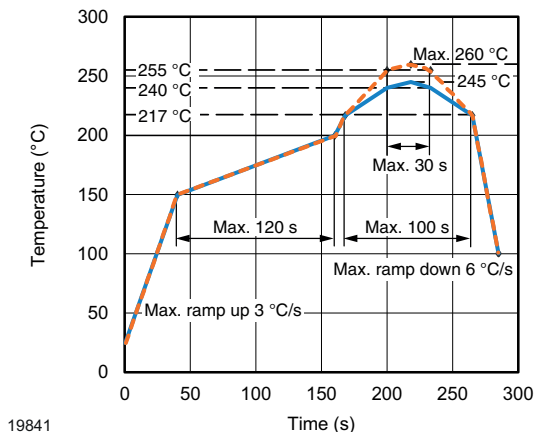
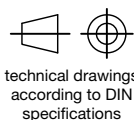
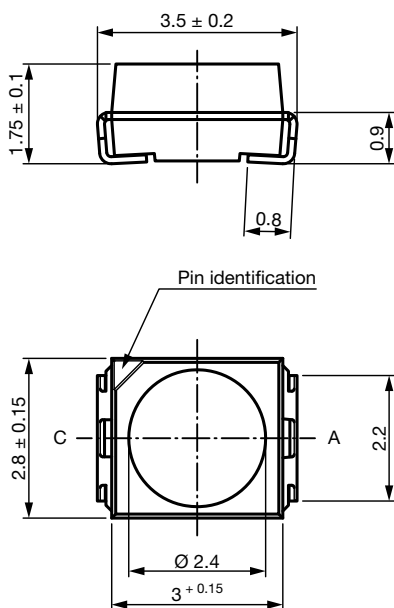
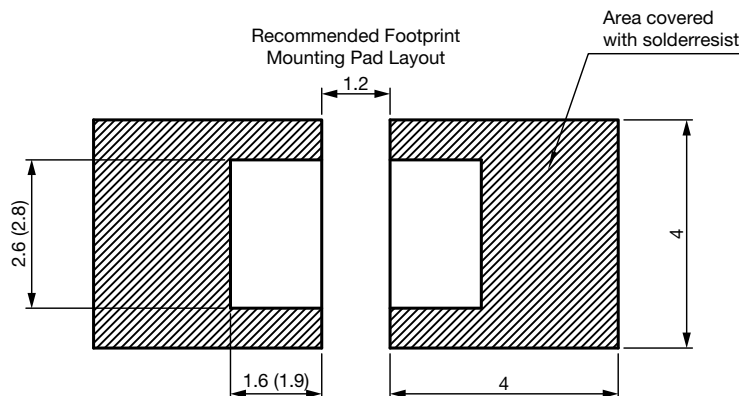


Fig. 8 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

## PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.541-5067.01-4  
Issue: 7; 12.03.14







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